

Properties	Standard	Unit	Dexnyl® PEEK SF Conductive
Density	ISO 1183	g/cm ³	1.4 +/- 0.01
Water Abs. (25°C 24h)	ISO 62	%	0,06
Mold shrinking percentage	3mm, 170°C, Flow direction	%	0.1
	Perpendicular to flow direction	%	0,5
Melting Point	DSC	°C	343
Distortion Temperature	ASTM D648	°C	315
Continuous Using Temperature	UL 74685	°C	260
Coefficient of thermal expansion	ASTM D696	10 ⁻⁵ /°C	1.5
Tensile strength (23°C)	ISO527-2/1B/50	Mpa	220
Tensile elongation (23°C)	ISO527-2/1B/50	%	1.8
Bending strength (23°C)	ISO 178	Mpa	298
Compressive strength (23°C)	ASTM D695	Mpa	240
Lzod impact strength (no gap)	ISO 180/U	kJm ⁻²	46
Rockwell hardness	ASTM D785	HRR	107
Flammable level	UL 94	V-0@mm	1.5
Surface resistivity		Ω	3x10 ⁶
Friction coefficient		μ	0.28

Distributed by

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The specified values are established from average values of several tests and they correspond to our today's knowledge. They are only to be used as information about our products and as help for the material selection. With these values, we do not ensure specific properties, or the suitability for certain application, therefore we do not assume any legal responsibility for an improper usage. The used test pieces have been machined from extruded semi-finished material. Since the plastic properties depend on the manufacturing process (extrusion, injection moulding), on the dimensions of the semi finished material and on the degree of crystallinity, the actual properties of a specific product may slightly deviate from the tested ones. For information about divergent properties do not hesitate to contact us. On request we advise you regarding the most appropriate component design and the definition of material specifications more suitable to your application data. Notwithstanding, the customer bears all the responsibility for the thorough examination of suitability, efficiency, efficacy and safety of the chosen products in pharmaceutical applications, medical devices or other end uses. Status: March 2020